

## CONFERENCES IN 2008:

Joint Int'l Conference on **Electronic Packaging Technology & High Density Packaging** (ICEPT-HDP) [www.icept.org](http://www.icept.org)  
July 28~31, 2008 Shanghai, China  
Contact: ICEPT-HDP Secretariat at [icept2008@fudan.edu.cn](mailto:icept2008@fudan.edu.cn)

Joint Event: 7th Int'l IEEE Conference on **Polymers and Adhesives in Microelectronics and Photonics** (POLYTRONIC 2008) with **PORTABLE 2008**  
August 17—22, 2008 Edelweiss Hotel & Conference Center [www.polytronic2008.com](http://www.polytronic2008.com)  
Garmisch-Partenkirchen, Germany  
Contact: [info@polytronic2008.com](mailto:info@polytronic2008.com)

**Electronics System-Integration Technology Conference** (ESTC 2008) [www.estc.biz](http://www.estc.biz)  
September 1-4, 2008; University of Greenwich  
Greenwich, London UK  
Contact: Chris Bailey, Greenwich University, [chris.bailey@estc.biz](mailto:chris.bailey@estc.biz)

4th Int'l **Workshop on Thermal Investigations of ICs and Systems (THERMINIC)**  
September 24-26, 2008 Rome, Italy  
Contact: Chantal Bénis-Morel, CMP, [chantal.benis@imag.fr](mailto:chantal.benis@imag.fr)

2008 Workshop on **Accelerated Stress Testing & Reliability** (ASTR)  
[www.ewh.ieee.org/soc/cpmt/tc7/ast2008](http://www.ewh.ieee.org/soc/cpmt/tc7/ast2008)  
October 1 - 3, 2008 Portland, OR USA  
Contact: Cheryl Tulkoff, National Instruments, [cheryl.tulkoff@ni.com](mailto:cheryl.tulkoff@ni.com)

Joint Event: 3rd **Int'l Microsystems, Packaging, Assembly and Circuits Technology** (IMPACT) Conference, with the 10th Int'l Conference on **Electronics Materials and Packaging** (EMAP) [www.impact-emap.org](http://www.impact-emap.org)  
October 22 - 24, 2008 Taipei, Taiwan  
Contact: Mr. Long-Shien Lin, [tw2008@isu.edu.tw](mailto:tw2008@isu.edu.tw)

54th IEEE **Holm Conference on Electrical Contacts** (HOLM 2008)  
[ewh.ieee.org/soc/cpmt/tc1/h2008/h2008top.html](http://ewh.ieee.org/soc/cpmt/tc1/h2008/h2008top.html)  
27-29 October, 2008 Orlando, FL USA  
Contact: Chi H. Leung, AMID DODUCO, [cleung@amidoduco.com](mailto:cleung@amidoduco.com)

**Electrical Performance of Electronic Packaging** (EPEP 2008)  
27-29 October, 2008 San Jose, CA USA  
Contact: Kelly, Univ of Arizona Professional Development, [epd@enr.arizona.edu](mailto:epd@enr.arizona.edu)

33rd Int'l **Electronics Manufacturing Technology Symposium** (IEMT 2008) [www.cpmt.ieemalaysia.org](http://www.cpmt.ieemalaysia.org)  
November 4-6, 2008; Penang, Malaysia  
Contact: Ir. Dr. Cheong Kuan Yew, USM [cheong@eng.usm.my](mailto:cheong@eng.usm.my)

9th **VLSI Packaging Workshop in Japan**  
December 1 - 2, 2008; Kyoto, Japan [vlsi-pkg-ws.org](http://vlsi-pkg-ws.org)  
Contact: Michitaka Kimura, Renesas Technology Corp, [kimura.michitaka@renesas.com](mailto:kimura.michitaka@renesas.com)

10th **Electronics Packaging Technology Conference** (EPTC 2008) [www.eptc-ieee.net](http://www.eptc-ieee.net)  
December 9-12, 2008; Singapore  
Contact: Dr. Tong Yan Tee, [tytee@amkor.com](mailto:tytee@amkor.com)

**Electrical Design of Advanced Packaging and Systems** (EDAPS 2008) [www.edaps2008.org](http://www.edaps2008.org)  
December 10-12, 2008 COEX Conference Center  
Seoul, Korea  
Papers due: July 31, 2008  
Contact: S.M Yang, [yangsm@ee.kaist.ac.kr](mailto:yangsm@ee.kaist.ac.kr)

2nd Int'l Conference on **Thermal issues in Emerging Technologies, Theory and Applications** (ThETA2)  
December 17-20, 2008 Cairo, Egypt [www.thetaconf.org](http://www.thetaconf.org)  
Papers due: July 31, 2008  
Contact: [thetaconf@gmail.com](mailto:thetaconf@gmail.com)

## CONFERENCES IN 2009:

2009 **Semiconductor Thermal Measurement and Management Symposium** (SEMI-THERM 25)  
March 15-19, 2009 San Jose, CA USA  
Abstracts due: October 15, 2008  
Contact: Tom Tarter, [ttarter@ieee.org](mailto:ttarter@ieee.org)

59th **Electronic Components and Technology Conference** (ECTC 2009)  
May 25-29, 2009 San Diego, CA USA  
Abstracts due: October 15, 2008  
Contact: Jean Trehwella, [jeanmh@us.ibm.com](mailto:jeanmh@us.ibm.com)

**European Microelectronics and Packaging Conference & Exhibition** (EMPC 2009) [www.empc2009.org](http://www.empc2009.org)  
June 14-17, 2009 Rimini, Italy  
Abstracts due: December 31, 2008  
Contact: Pragma Congressi, [segreteria@empc2009.org](mailto:segreteria@empc2009.org)

IEEE **Int'l Workshop On Advances in Sensors and Interfaces** (IWASI'09)  
June 25-26, 2009 Trani, Italy  
Papers due: February 28, 2009  
Contact: Prof. Daniela De Venuto, [d.devenuto@poliba.it](mailto:d.devenuto@poliba.it)